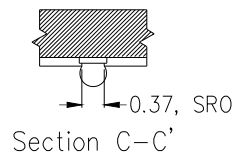
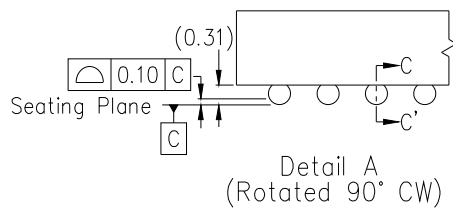
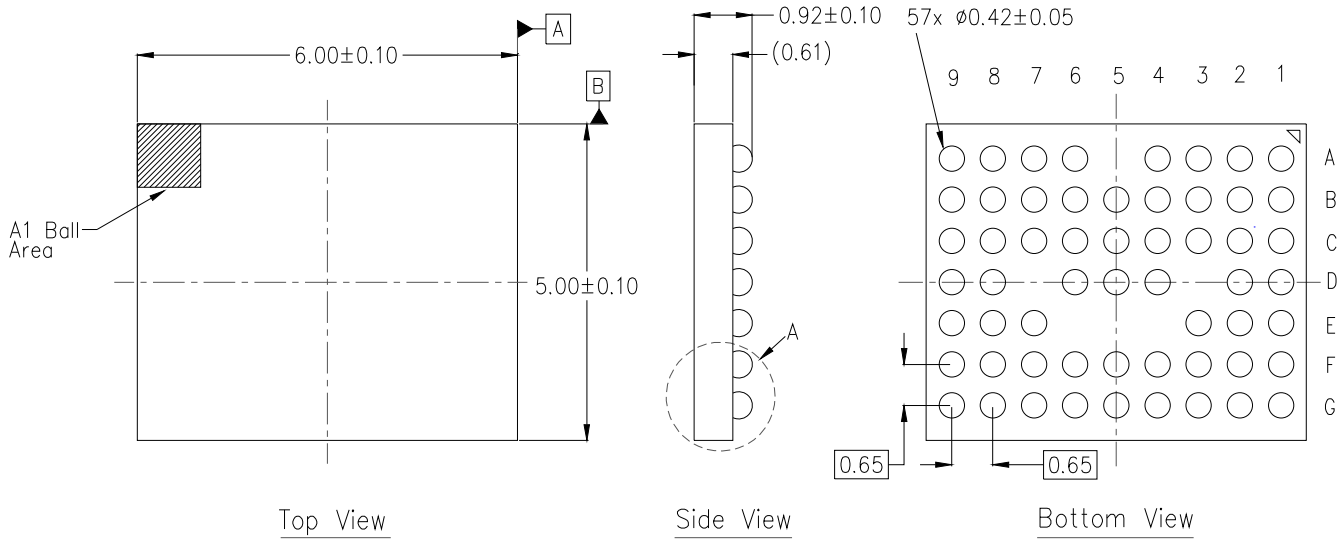


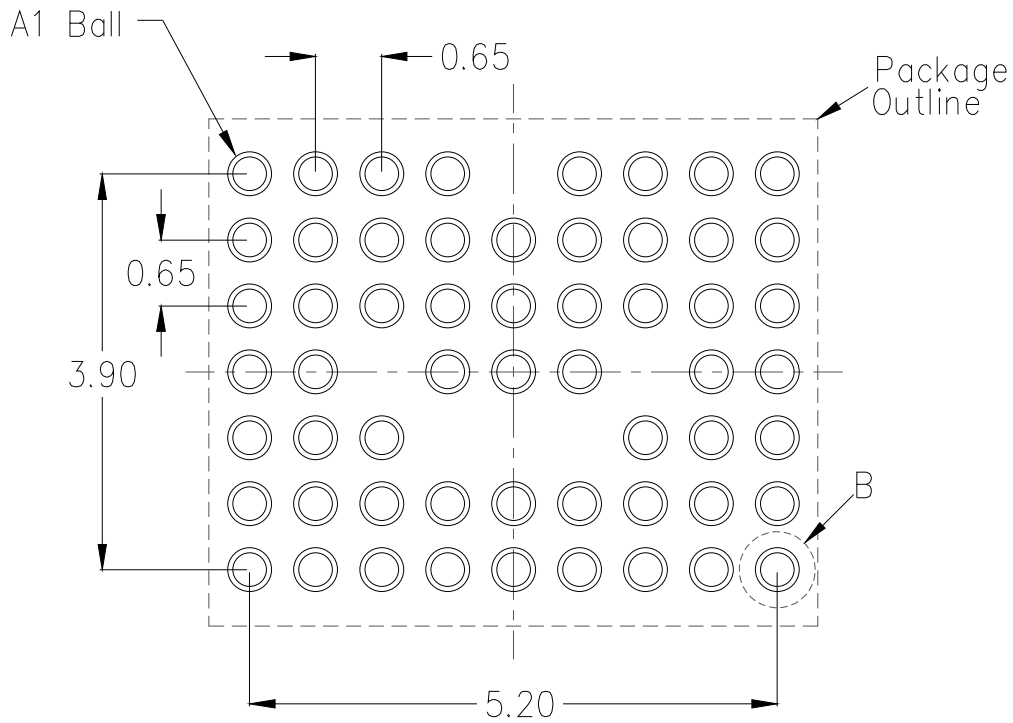
57- FCCSP, Package Outline Drawing



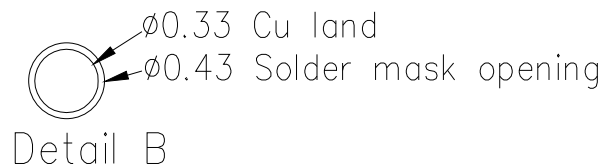
6.0x5.0x0.92 mm Body, 0.65 mm Pitch

AVG57D1, PSC-4892-01, Rev00, Page 1





Recommended Land Pattern
 (PCB Top View, NSMD Design)



NOTES:

1. JEDEC compatible.
2. All dimensions are in mm and angles are in degrees.
3. Use ± 0.05 mm tolerance for all other dimensions.
4. Numbers in () are for references only.
5. Pre-reflow solderball diameter is $\phi 0.4$ mm.

Package Revision History		
Date Created	Rev No.	Description
Oct 26, 2021	Rev 00	Initial Release